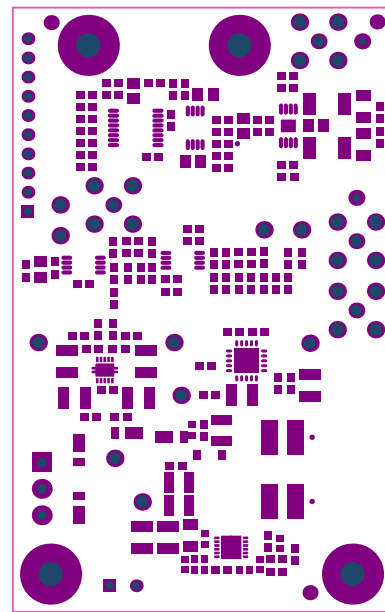
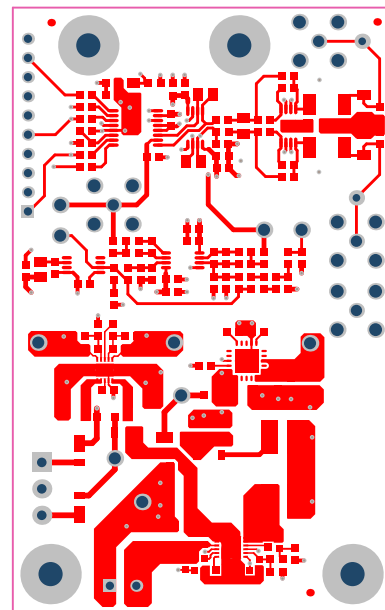


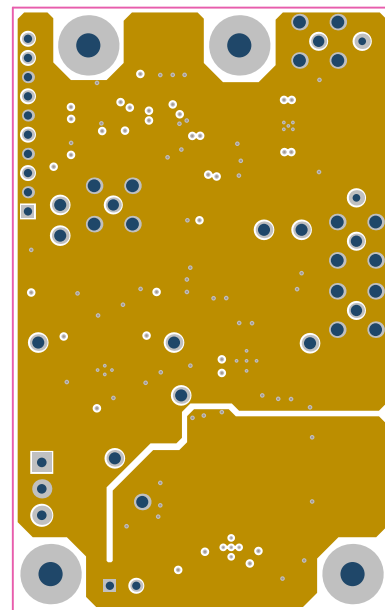
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01427	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01427		
PLOT NAME = Top Overlay	GENERATED : 6/23/2017 11:19:49 AM	TEXAS INSTRUMENTS	



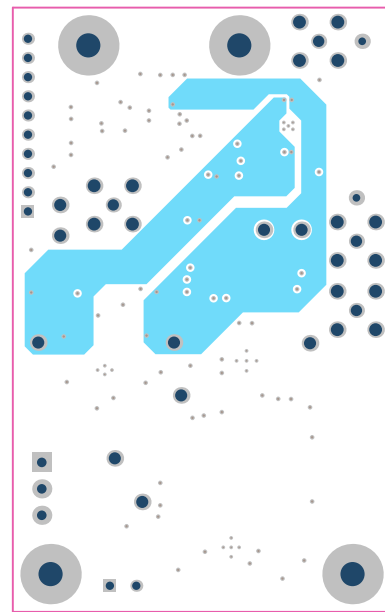
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01427	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01427		
PLOT NAME = Top Solder Mask	GENERATED : 6/23/2017 11:19:51 AM	TEXAS INSTRUMENTS	



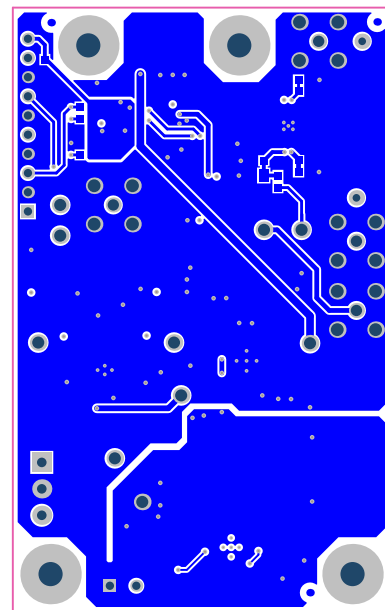
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01427	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01427		
PLOT NAME = Top Layer	GENERATED : 6/23/2017 11:19:52 AM	TEXAS INSTRUMENTS	



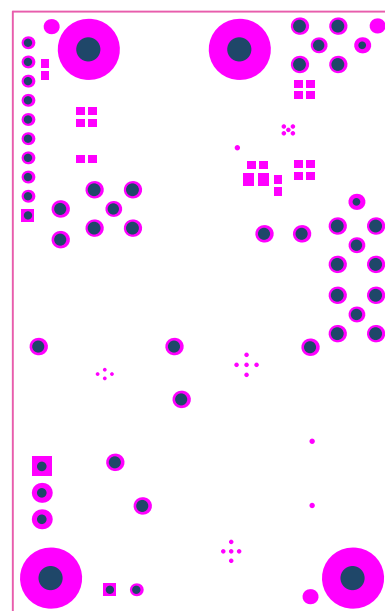
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01427	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = GND	TID #: TIDA-01427		
PLOT NAME = Signal Layer 1	GENERATED : 6/23/2017 11:19:53 AM	TEXAS INSTRUMENTS	



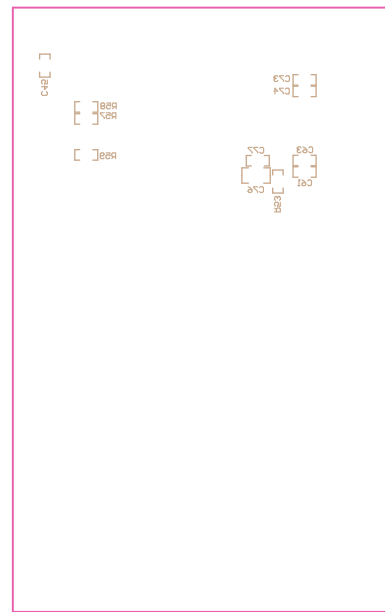
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01427	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = PWR	TID #: TIDA-01427		
PLOT NAME = Signal Layer 2	GENERATED : 6/23/2017 11:19:54 AM	TEXAS INSTRUMENTS	



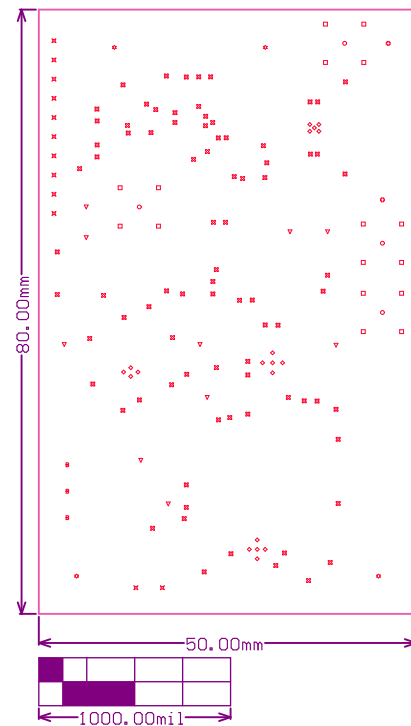
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01427	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01427		
PLOT NAME = Bottom Layer	GENERATED : 6/23/2017 11:19:54 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01427	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01427		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/23/2017 11:19:55 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01427	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01427		
PLOT NAME = Bottom Overlay	GENERATED : 6/23/2017 11:19:57 AM	TEXAS INSTRUMENTS	



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair
⊕	2	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer
B	3	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer
O	4	59.06mil (1.500mm)	PTH	Round	Top Layer - Bottom Layer
☆	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer
▽	10	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer
⊗	12	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer
□	16	66.93mil (1.700mm)	PTH	Round	Top Layer - Bottom Layer
◇	19	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer
⊗	83	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer
	153 Total				

DRILL TABLE
 FOR 7.874MIL DRILL +0/-7.874MIL
 FOR 12MIL DRILL +0/-12MIL
 FOR PTH DRILL +/-3MIL

NOTE:
 12MIL Vias are Tented in both the sides.
 7.874MIL vias are not Tented.

This is not an Impedance controlled board.

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01427	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01427		
PLOT NAME = Drill Drawing	GENERATED : 6/23/2017	11:19:59 AM	TEXAS INSTRUMENTS

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